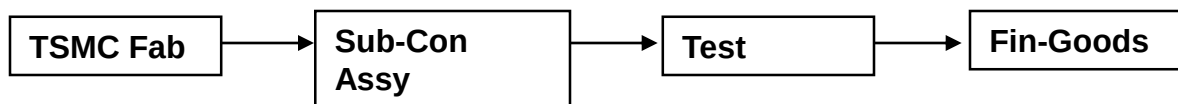


QUALIFICATION RESULTS SUMMARY OF FAB TRANSFER AT ADI PER PCN 17_0142			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	1*77	Passed
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	1*77	Passed
Autoclave	JEDEC <i>JESD22-A102</i>	1*77	Passed
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	1*77	Passed
Early Life Failure (ELF)	MIL-STD-883 <i>Method 1015</i>	3*667	Passed
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1*45	Passed
Solder Heat Resistance (SHR)*	<i>ADI-0049</i>	1*30	Passed
Latch-Up	JEDEC <i>JESD78</i>	6	Passed
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JDS-001-2011</i>	3/voltage	Passed
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	Passed

*Preconditioned per JEDEC/IPC J-STD-020

Alternate fab source for RS-232 and RS-485/RS-422 Transceiver products. To enable additional wafer fabrication capacity

Current Flow:



Alternate Flow:

